# **MSL** with Slitted Ground

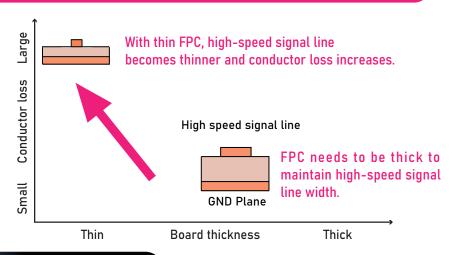
FPCs are expected to be thinner while maintaining transmission characteristics by providing slit design in ground (GND) plane.

#### **Product Characteristics**

- This technology under development eliminates the relationship between FPC thickness and conductor loss, a problem of microstripline.
- It has been difficult to maintain the transmission characteristics until now, because the conductor loss increases as the FPC becomes thinner.

### Microstripline (MSL) structural problem

In the conventional structure, reducing the thickness of a FPC results in a thinner high-speed signal width and greater conductor loss, making it difficult to make a FPC thinner while maintaining its transmission characteristics.



# **Transmission characteristics (S21 measurement)**

## Provide thinner FPC while maintaining the transmission characteristics!

